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2026 CONFERENCES FOR INTELLIGENT MANUFACTURING INDUSTRY



Ringier organizes high level technical and business conferences bringing industry leaders together for information exchange and networking opportunities in the Intelligent Manufacturing industry.

- 2026 ASEAN High-Performance Machining Summit —Autoparts, Electronics, Assembly automation (Mar 10-11,Ho Chi Minh, Vietnam)
- Advanced Manufacturing Industry Development Conference 2026(Apr,Chengdu China)
- AI Intelligent Manufacturing Innovation Application Summit 2026(June,Suzhou China)
- 2026 eVTOL Key Technology and Manufacturing Industry Development Conference(Jul .,Chongqing China)
- Aircraft Manufacturing and Component Processing Technology Forum 2026(Aug,Xi'an China)
- 2026 ASEAN Advanced Automotive Manufacturing Summit - Flexible Production & EV Solutions(Nov. 3-4,Cikarang, Indonesia)



Industry and Magazine e-Newsletters

Scheduled industry and magazine e-newsletters targeting specific industries, job functions and decision making responsibilities in China and S. E. Asia deliver relevant news to industry leaders or engineers throughout the year providing insightful and valuable content that readers rely on. It brings your message to the place your target audience visits most – their inbox. Generate immediate response and website traffic by promoting your key products and services by direct communications with your core target audiences.

Language: Simplified Chinese
Frequency : 12x per year
Readership: 113,600

ISSUE	January	February	March	April	May	June
Topic	Embodied Intelligence AI Algorithm	Cloud Computing Digital Twins	Intelligent Detection Annual Update of Lighthouse Factory	Industrial Control Technology Servo System	Smart Wearable Devices IIoT	Semiconductor Smart Manufacturing Smart Packaging
ISSUE	July	August	September	October	November	December
Topic	Robot AMR/AGV	Intelligent Assembly Humanoid Robot	Flexible Manufacturing Technology Automotive Smart Manufacturing	Sensor Machine Vision	eVTOL Aircraft Predictive Maintenance	Intelligent Warehousing and Logistics Industrial Software

iConnect e-Newsletters

iConnect e-Newsletters bring together all of the latest and best content on a specific topic. Each e-Newsletter provides its sponsors with a cost-effective opportunity to build category thought leadership among a qualified audience of buyers.

Robotics

Language: Simplified Chinese, Frequency : 6x per year, Readership: 38,500

ISSUE	February	April	June	August	October	December
Topic	Industrial Robotics Market 2026 Outlook	Humanoid Robot +Dexterous Hand	Embodied AI & Robotics Joint module & Reducer	Cobots+AI in Industrial Applications	Industrial Robot+ Automobile Manufacturing + Electronics Manufacturing/Medical- New Technologies and Case Studies	Year-End Robotics Review Smart Warehousing

Automation in Food & Beverage

Language: Simplified Chinese, Frequency : 6x per year, Readership : 17,650

ISSUE	January	March	May	July	September	November
Topic	Industry 4.0 in F&B Processing	Intelligent Manufacturing in Beverage Industry	Robotics	Digital Twins Optimizing Production Processes	AI-Driven Process Control	F&B Factory in The Future

Electronic Chip Design & Manufacturing

Language: Simplified Chinese, Frequency : 4x per year, Readership: 14,380

ISSUE	February	May	August	October
Topic	Decoding Wafer Fabrication Technologies Comprehensive Guide to Semiconductor Materials	AI Chip Design Critical Perspectives on Automotive-Grade Chip Design	Automation in Wafer Fabrication	Semiconductor Design Software Exhibition

Motion Control

Language: Simplified Chinese, Frequency : 4x per year, Readership: 26,580

ISSUE	March	June	September	December
Topic	Motion Control+ AI Industrial Robot	Motion Control+ eVTOL Handling & Packing	Motion Control+F&B Servo System + Semiconductor	Motion Control+ CNC+Robotics 2026 Motion Control Market Outlook

Sensor Design and Applications

Language: Simplified Chinese, Frequency : 4x per year, Readership: 34,680

ISSUE	January	April	July	October
Topic	Robot sensors	Intelligent Sensors	MEMS Sensor	Machine Vision Sensor

Electronic Chip Packaging & Testing

Language: Simplified Chinese, Frequency : 6x per year, Readership: 12,960

ISSUE	January	April	July	September	November	December
Topic	Annual Review: AI in Semiconductor Manufacturing Annual Review of AI in Chip Packaging and Testing	Optical Inspection Upgrade Breakthroughs in Photonic Integrated Circuits	Automotive Chip Packaging Process Technologies Automotive Chip Interconnect Technologies	Breakdown of Cutting-Edge Semiconductor Test & Packaging Tools Smart Semiconductor Manufacturing Line	Intelligent Chip Testing Technologies AI-Based Chip Quality Inspection	Advanced Packaging Breakthrough Compound Semiconductor Demo Showcase